
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Mostafazadeh et al.

Attorney Docket No.: NSC1P226R

Patent No.: 6,034,423

Issued: March 7, 2000

Title: LEADFRAM DESIGN FOR INCREASED
CHIP PINOUT

Box Reissue
Commissioner for Patents
Washington, DC 20231

REISSUE APPLICATION DECLARATION BY INVENTORS

As a below-named inventor, I hereby declare that:

1. My residence and citizenship are stated below next to my name.

2. I have reviewed and understand the contents of the specification and claims of the above-identified reissue application, and believe myself to be the original, first, and a joint inventor of the invention described and claimed in the aforesaid reissue application and in U.S. Letters Patent No. 6,034,423 on which said reissue application is based.

3. I do not know and do not believe that said invention was ever known or used in the United States of America before the invention thereof by myself.

4. I acknowledge a duty to disclose information I am aware of which is material to patentability as defined in 37 C.F.R. § 1.56.

5. I believe that the original patent, U.S. Patent No. 6,034,423, is partly inoperative as the patent claims less than I had the right to claim in the patent. As an example, the patent failed to broadly claim the bus bar in an exposed lead environment aspect of the invention.

6. All errors being corrected in this reissue arose without any deceptive intent on my part.

I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 10/31/01

Shahram Mostafazadeh
Shahram Mostafazadeh

4238 Monet Circle

San Jose, CA 95136
Residence Address

United States of America
Citizenship and Country of Residence

Date: 10/31/01

Joseph O. Smith
Joseph O. Smith

16915 John Telfer Drive

Morgan Hill, CA 95037
Residence Address

United States of America
Citizenship and Country of Residence

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CERTIFICATE OF EXPRESS MAILING

I hereby certify that this paper and the documents and/or fees referred to as attached therein are being deposited with the United States Postal Service on Dec. 10, 2001 in an envelope as "Express Mail Post Office to Addressee" service under 37 CFR §1.10, Mailing Label Number ET5824833854S, addressed to the Commissioner for Patents, Washington, DC 20231.


Jeena McLeod

POWER OF ATTORNEY BY ASSIGNEE

Commissioner for Patents
Washington, D. C. 20231

Sir:

National Semiconductor Corporation ("assignee"), a Delaware corporation having a place of business at 2900 Semiconductor Drive, certifies that to the best of assignee's knowledge and belief it is the assignee of the entire right, title, and interest in and to the above-referenced patent application and represents that the undersigned is a representative authorized and empowered to sign on behalf of the assignee.

Assignee has reviewed the assignment documents that evidence the placement of title in the assignee, true and correct copies of which are attached hereto, and understands and believes that these assignment documents will be submitted for recordation in the U.S. Patent and Trademark Office.

Assignee hereby appoint the law firm of Beyer Weaver & Thomas, LLP and all practitioners who are associated with the Customer Number 022434 as my principal attorneys to

prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

This power of attorney is being given by Christopher J. Byrne, to the legal representatives of National Semiconductor Corporation, a licensee of the above-identified patent, which has the right to prosecute this application.

Please send all correspondence for this application as follows:

Steve D Beyer
P.O. Box 778
Berkeley, CA 94704-0778


Please direct any calls to the same at (650) 961-8300.

Assignee of Interest:

National Semiconductor Corporation
2900 Semiconductor Drive
Santa Clara, CA 95051

Date

11/27/01


Christopher J. Byrne

Director of Intellectual Property and Technology Licensing

10016750-121001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Mostafazadeh et al.

Attorney Docket No.: NSC1P226R

Original Patent No.: 6,034,423

Original Patent Issue Date: March 7, 2000

For: LEAD FRAME DESIGN FOR INCREASED
CHIP PINOUT

**Establishing Right Of Assignee To Take Action
and Consent Of Assignee
under 37 C.F.R. 1.172(a) and 3.73(b)**

Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

The assignee of the entire right, title and interest hereby seeks to take action in the Patent and Trademark Office in this matter.

IDENTIFICATION OF ASSIGNEE

The assignee of the entire right, title and interest of the above-identified application/patent is held by National Semiconductor Corporation.

BASIS OF ASSIGNEE'S INTEREST

Ownership by the assignee is established by assignment document recorded at reel 9125, frame 0299. A copy of the assignment is attached hereto.

DECLARATIONS

I, the undersigned, have reviewed all of the evidentiary documents for the above-identified application, and, to the best of my knowledge and belief, title is in the assignee seeking to take this action.

I hereby declare that all statements made herein of my own knowledge are true, and that all statements made on information and belief are believed to be true; and further, that these statements are made with the knowledge that willful false statements, and the like so made, are

punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

ASSENT OF ASSIGNEE

National Semiconductor Corporation, owner of U.S. Patent No. 6,034,423 by virtue of the assignment document referenced above, hereby assents to the filing of an application for reissue of said patent and to the issuance of a reissue patent therefor.

Date:

11/27/01



Christopher J. Byrne
Director of Intellectual Property and Technology
Licensing
National Semiconductor Corporation